Claims

- [c1] What is claimed is:
 - 1.A connector for connecting a first board to a second board, the connector comprising: at least one conductive media comprising: a plurality of insulating layers; and a plurality of conductive layers, wherein each conductive layer is formed between two insulating layers; and a frame comprising a hollow space for holding the conductive media.
- [c2] 2.The connector of claim 1 wherein the conductive media is rectangular cubic shaped.
- [c3] 3.The connector of claim 1 wherein the frame comprises an upper frame fixed to the second board and a lower frame fixed to the first board.
- [c4] 4.The connector of claim 3 wherein the upper frame has an upper hook and the lower frame has a lower hook for being connected to the upper hook.
- [05] 5.The connector of claim 1 wherein the first board is fixed to the frame through a top plug connection.

- [c6] 6.The connector of claim 3 wherein the upper side of the conductive layer is connected to a goldfinger on the second board through a metal connecting point on the upper frame, and the lower side of the conductive layer is connected to a goldfinger on the first board through a metal connecting point on the lower frame, in order to transmit electric signals between the first board and the second board.
- [c7] 7.The connector of claim 1 wherein the frame is a plastic frame.
- [08] 8.The connector of claim 1 wherein the upper side of the conductive layer is connected to a goldfinger on the second board, and the lower side of the conductive layer is connected to a goldfinger on the first board, in order to transmit electric signals between the first board and the second board.
- [09] 9.The connector of claim 1 wherein the second board is a printed circuit board.
- [c10] 10.The connector of claim 1 wherein the first board is an interface card.
- [c11] 11.The connector of claim 1 wherein the conductive layers are formed by conductive ceramic particles.

- [c12] 12.The connector of claim 1 wherein the conductive layers are formed by conductive metal particles.
- [c13] 13.The connector of claim 1 wherein the conductive layers are conductive metal lines.
- [c14] 14.The connector of claim 1 wherein the insulating layers are formed by insulating rubber.
- [c15] 15.The connector of claim 1 wherein the insulating layers are formed by insulating ceramic materials.